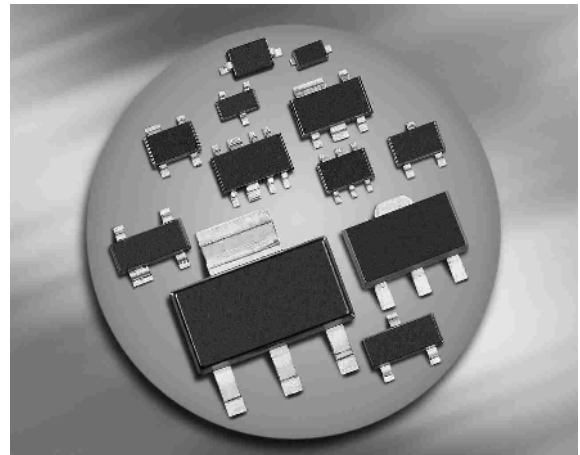
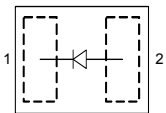


**Low VF Schottky Diode**

- Reverse voltage: 30 V
- Forward current: 1 A
- Low forward voltage and smallest package form factor (1.0 x 0.6 x < 4 mm) for mobile phone battery charger application
- Pb-free (RoHS compliant) package


**BAS3010S-02LRH**


Type	Package	Configuration	Marking
BAS3010S-02LRH	TSLP-2-17	single	1T

**Maximum Ratings at  $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Value	Unit
Diode reverse voltage <sup>1)</sup>	$V_R$	30	V
Forward current <sup>1)</sup> , $T_S \leq 114\text{ }^\circ\text{C}$	$I_F$	1	A
Non-repetitive peak surge forward current ( $t_p \leq 10\text{ ms}$ )	$I_{FSM}$	4	
Junction temperature	$T_j$	150	$^\circ\text{C}$
Operating temperature range	$T_{op}$	-55 ... 150	
Storage temperature	$T_{stg}$	-65 ... 150	

**Thermal Resistance**

Junction - soldering point <sup>2)</sup>	$R_{thJS}$	$\leq 60$	K/W
--	------------	-----------	-----

<sup>1</sup>For  $T_A > 25\text{ }^\circ\text{C}$  the derating of  $V_R$  and  $I_F$  has to be considered

<sup>2</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

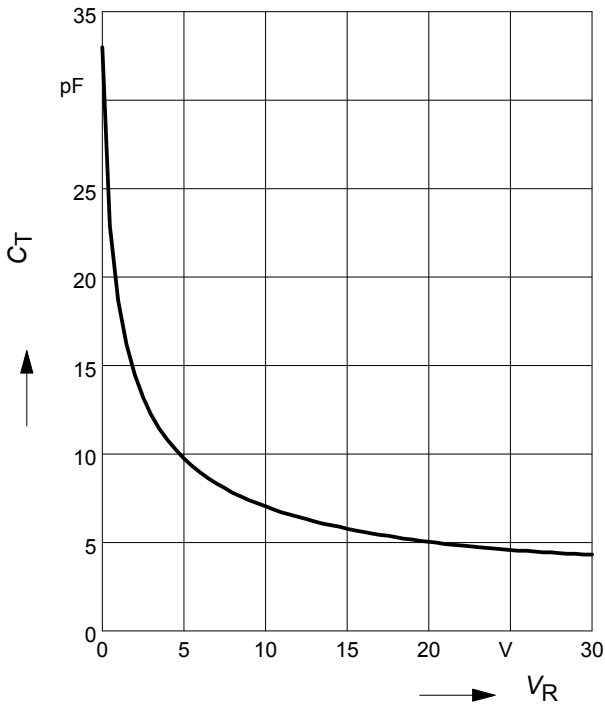
**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Reverse current <sup>1)</sup> $V_R = 10\text{ V}$ $V_R = 30\text{ V}$	$I_R$	- -	- -	30 300	$\mu\text{A}$
Forward voltage <sup>1)</sup> $I_F = 1\text{ mA}$ $I_F = 100\text{ mA}$ $I_F = 700\text{ mA}$ $I_F = 1000\text{ mA}$	$V_F$	- - - -	200 340 500 570	250 390 570 650	mV
<b>AC Characteristics</b>					
Diode capacitance $V_R = 5\text{ V}, f = 1\text{ MHz}$	$C_T$	-	10	15	pF

<sup>1)</sup>Pulsed test:  $t_p = 300\ \mu\text{s}; D = 0.01$

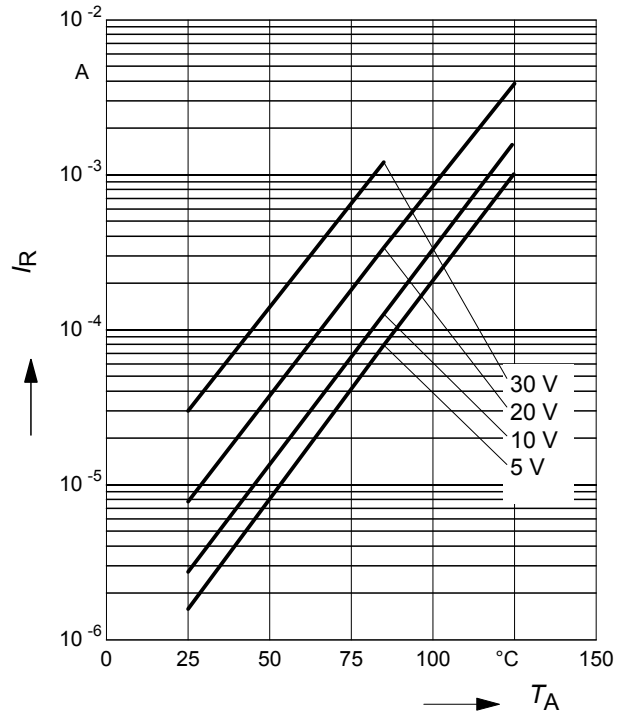
**Diode capacitance  $C_T = f(V_R)$**

$f = 1\text{MHz}$



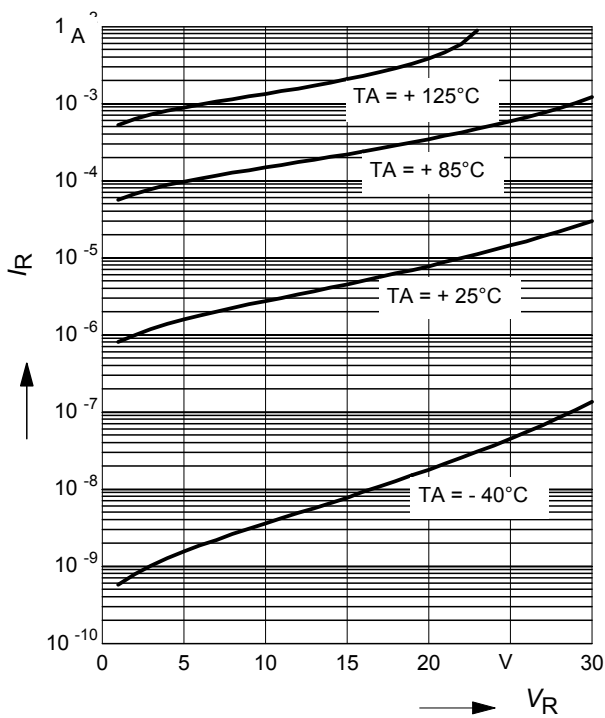
**Reverse current  $I_R = f(T_A)$**

$V_R = \text{Parameter}$



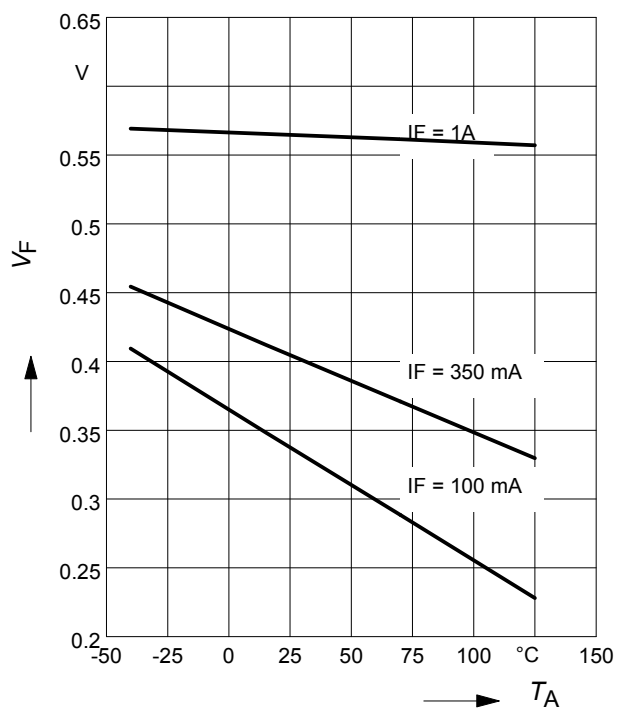
**Reverse current  $I_R = f(V_R)$**

$T_A = \text{Parameter}$

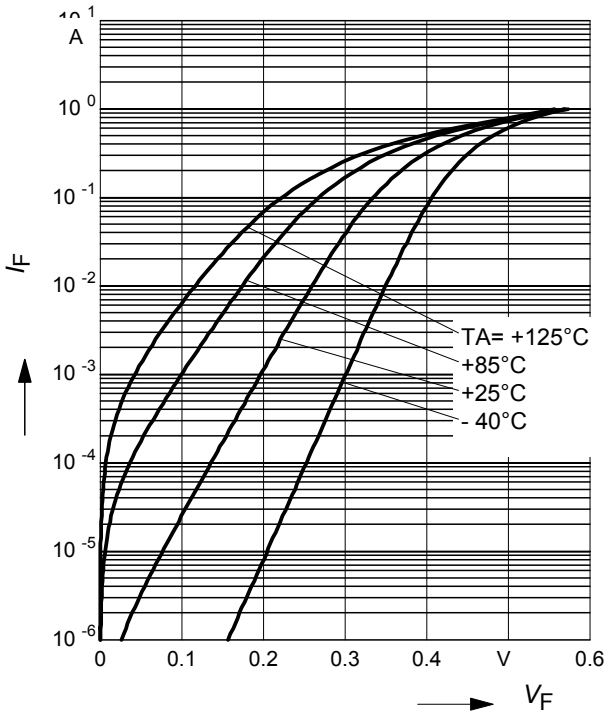


**Forward Voltage  $V_F = f(T_A)$**

$I_F = \text{Parameter}$



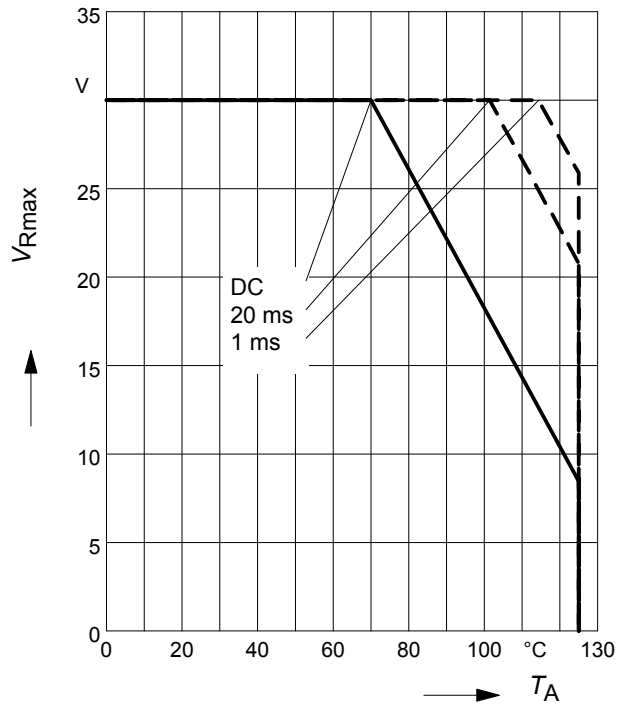
**Forward current  $I_F = f(V_F)$**



**Permissible Reverse voltage  $V_R = f(T_A)$**

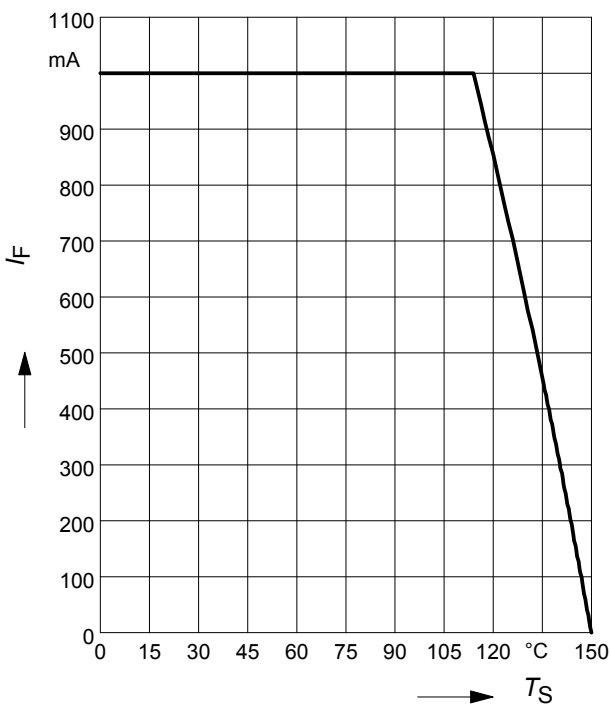
$t_p$  = Parameter, Duty cycle < 0.01

Device mounted on PCB with  $R_{th} = 160 \text{ K/W}$

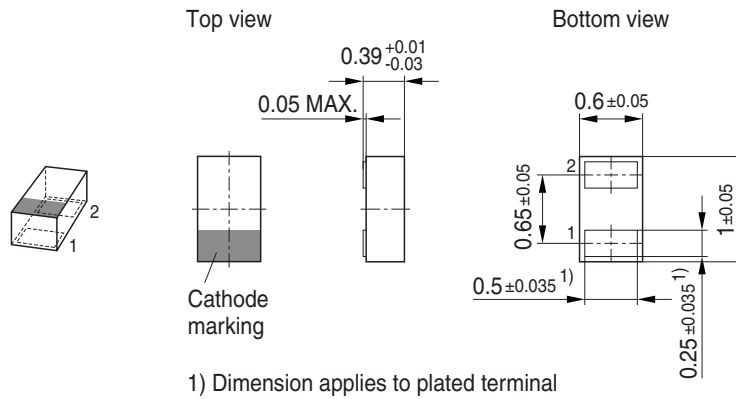


**Forward current  $I_F = f(T_S)$**

BAS3010S-02LRH

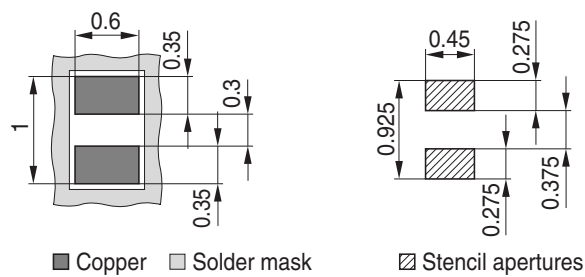


### Package Outline

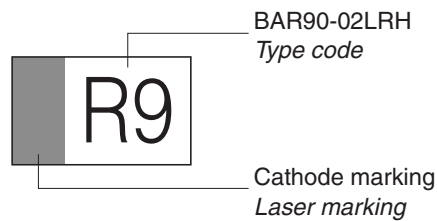


### Foot Print

For board assembly information please refer to Infineon website "Packages"

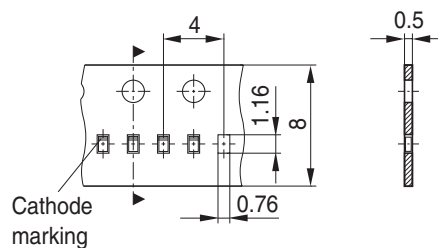


### Marking Layout (Example)



### Standard Packing

Reel  $\varnothing$ 180 mm = 15.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 50.000 Pieces/Reel (optional)



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